

BALL CONTACT FOR FLIP-CHIP DEVICES**ABSTRACT**

A contact (11) for a semiconductor device (10) or passive substrate is made up of an array of conductive balls (12), the individual balls (12) of the contact (11) being a compressible material coated with a metal conductive material. The balls (12) in the array are compressed while being bonded to the contact area to provide a larger bond area between the ball (12) and the contact area to which it is bonded.

Figure 1.

TI-16890 EU

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This Sheet Has Been Replaced:

